



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Jion-Ping Lu, et al.

Serial No.: 10/608,921

Filed: 06/27/03

For: Copper Surface Passivation During Semiconductor Manufacturing

TI-35330

Examiner: TBD

Art Unit: 2812

**LETTER TO THE OFFICIAL DRAFTSPERSON**

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

*Karen Vertz*  
Karen Vertz

*10-10-03*  
Date

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Enclosed are **THREE (3)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Respectfully submitted,

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